



ISOCOM
COMPONENTS

ICPLW2601, ICPLW2611



DESCRIPTION

The ICPLW2601 and ICPLW2611 devices each consists of an infrared emitting diode optically coupled to a high speed integrated photo detector logic gate with a strobable output.

These devices belong to Isocom wide body package range optocouplers.

FEATURES

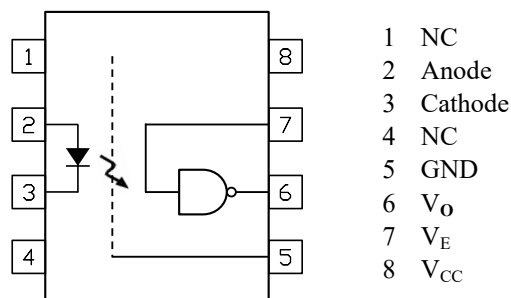
- High Speed 10Mbit/s
- Wide Body Package
- Guaranteed Performance from -40°C to 85°C
- Storable Logic Gate Output
- Minimum Common Mode Transient Immunity $10\text{kV}/\mu\text{s}$ at V_{CM} 1000V (ICPLW2611)
- High AC Isolation Voltage $5000V_{\text{RMS}}$
- Pb Free and RoHS Compliant
- Safety Approvals Pending

APPLICATIONS

- Line Receivers, Data Communication
- LSTTL to TTL, LSTTL or 5V CMOS
- Data Multiplexing
- Pulse Transformer Replacement
- Switch Mode Power Supplies
- Ground Loop Elimination
- Computer Peripheral Interface

ORDER INFORMATION

- Add SM after PN for Surface Mount
- Add SMT&R after PN for Surface Mount Tape & Reel



A $0.1\mu\text{F}$ bypass Capacitor must be connected between Pins 8 and 5.

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^{\circ}\text{C}$)

Stresses exceeding the absolute maximum ratings can cause permanent damage to the device. Exposure to absolute maximum ratings for long periods of time can adversely affect reliability.

Input

Forward Current	50mA
Reverse Voltage	5V
Power dissipation	100mW

Output

Output Current	50mA
Output Voltage	7.0V
Supply Voltage	7.0V
Enable Input Voltage (maximum 500mV above V_{CC})	5.5V
Power Dissipation	85mW

Total Package

Isolation Voltage	$5000V_{\text{RMS}}$
Operating Temperature	-40 to 85°C
Junction Temperature	125°C
Storage Temperature	-55 to 125°C
Lead Soldering Temperature (10s)	260°C

ISOCOM COMPONENTS 2004 LTD

Unit 25B, Park View Road West, Park View Industrial Estate
Hartlepool, Cleveland, TS25 1PE, United Kingdom
Tel : +44 (0)1429 863 609 Fax : +44 (0)1429 863 581
e-mail : sales@isocom.co.uk
<http://www.isocom.com>

ISOCOM COMPONENTS ASIA LTD

Hong Kong Office
Block A, 8/F, Wah Hing Industrial Mansions
36 Tai Yau Street, San Po Kong, Kowloon, Hong Kong
Tel : +852 2995 9217 Fax : +852 8161 6292
e-mail : sales@isocom.com.hk

ICPLW2601, ICPLW2611**Truth Table (Positive Logic)**

Input	Enable	Output
H	H	L
L	H	H
H	L	H
L	L	H
H	NC	L
L	NC	H

ICPLW2601, ICPLW2611

ELECTRICAL CHARACTERISTICS ($T_A = -40$ to 85°C unless otherwise specified)

INPUT

Parameter	Symbol	Test Condition	Min	Typ.	Max	Unit
Forward Voltage	V_F	$I_F = 10\text{mA}$		1.4	1.8	V
Forward Voltage Temperature Coefficient	$\Delta V_F / \Delta T$	$I_F = 10\text{mA}$		-1.9		mV/ $^\circ\text{C}$
Reverse Voltage	V_R	$I_R = 100\mu\text{A}$, $T_A = 25^\circ\text{C}$	5.0			V
Input Capacitance	C_{IN}	$V_F = 0\text{V}$, $f = 1\text{MHz}$		70		pF

OUTPUT

Parameter	Symbol	Test Condition	Min	Typ.	Max	Unit
Low Level Supply Current	I_{CCH}	$I_F = 0\text{mA}$, $V_{CC} = 5.5\text{V}$ $V_E = 0.5\text{V}$		6.5	10	mA
Low Level Supply Current	I_{CCL}	$I_F = 10\text{mA}$, $V_{CC} = 5.5\text{V}$ $V_E = 0.5\text{V}$		8	13	mA
High Level Enable Current	I_{EH}	$V_{CC} = 5.5\text{V}$, $V_E = 2.0\text{V}$		-0.6	-1.6	mA
Low Level Enable Current	I_{EL}	$V_{CC} = 5.5\text{V}$, $V_E = 0.5\text{V}$		-0.8	-1.6	mA
High Level Enable Voltage	V_{EH}	$I_F = 10\text{mA}$, $V_{CC} = 5.5\text{V}$	2.0			V
Low Level Enable Voltage	V_{EL}	$I_F = 10\text{mA}$, $V_{CC} = 5.5\text{V}$			0.8	V

COUPLED

Parameter	Symbol	Test Condition	Min	Typ.	Max	Unit
High Level Output Current	I_{OH}	$I_F = 250\mu\text{A}$, $V_E = 2.0\text{V}$ $V_{CC} = V_O = 5.5\text{V}$		2.1	100	μA
Low Level Output Voltage	V_{OL}	$I_F = 5\text{mA}$, $V_E = 2.0\text{V}$ $V_{CC} = 5.5\text{V}$, $I_{OL} = 13\text{mA}$		0.35	0.6	V
Input Threshold Current	I_{FT}	$V_{CC} = 5.5\text{V}$, $V_E = 2.0\text{V}$ $V_O = 0.6\text{V}$, $I_{OL} = 13\text{mA}$		3.0	5	mA

ICPLW2601, ICPLW2611

ELECTRICAL CHARACTERISTICS ($T_A = -40$ to 85°C , $V_{CC} = 5\text{V}$, $I_F = 7.5\text{mA}$
 unless otherwise specified)

SWITCHING

Parameter	Symbol	Test Condition	Min	Typ.	Max	Unit
Propagation Delay Time to High Output Level	t_{PHL}	$R_L = 350\Omega$ $C_L = 15\text{pF}$ $T_A = 25^\circ\text{C}$		35	100	ns
Propagation Delay Time to Low Output Level	t_{PLH}			40	100	
Pulse Width Distortion	$ t_{PHL} - t_{PLH} $	$R_L = 350\Omega$ $C_L = 15\text{pF}$		5	40	
Output Rise Time (10% to 90%)	t_r			40		
Output Fall Time (90% to 10%)	t_f			10		
Enable Propagation Delay Time to High Output Level	t_{ELH}	$V_{EH} = 3.0\text{V}$ $R_L = 350\Omega$ $C_L = 15\text{pF}$		15		
Enable Propagation Delay Time to Low Output Level	t_{EHL}			15		

ICPLW2601, ICPLW2611

ELECTRICAL CHARACTERISTICS ($T_A = -40$ to 85°C , $V_{CC} = 5\text{V}$, $I_F = 7.5\text{mA}$ unless otherwise specified)

SWITCHING

Parameter	Symbol	Test Condition	Min	Typ.	Max	Unit
Common Mode Transient Immunity at Logic High	CM_H	ICPLW2601 $I_F = 0\text{mA}$, $V_{OH} = 2.0\text{V}$ $R_L = 350\Omega$ $V_{CM} = 50\text{Vp-p}$ $T_A = 25^\circ\text{C}$	5			$\text{kV}/\mu\text{s}$
		ICPLW2611 $I_F = 0\text{mA}$, $V_{OH} = 2.0\text{V}$ $R_L = 350\Omega$ $V_{CM} = 400\text{Vp-p}$ $T_A = 25^\circ\text{C}$	10			
		ICPLW2611 $I_F = 0\text{mA}$, $V_{OH} = 2.0\text{V}$ $V_E = V_{CC}$ $R_L = 350\Omega$ $V_{CM} = 400\text{Vp-p}$ $T_A = 25^\circ\text{C}$	20			
Common Mode Transient Immunity at Logic Low	CM_L	ICPLW2601 $I_F = 7.5\text{mA}$, $V_{OL} = 0.8\text{V}$ $R_L = 350\Omega$ $V_{CM} = 50\text{Vp-p}$ $T_A = 25^\circ\text{C}$	5			$\text{kV}/\mu\text{s}$
		ICPLW2611 $I_F = 7.5\text{mA}$, $V_{OL} = 0.8\text{V}$ $R_L = 350\Omega$ $V_{CM} = 400\text{Vp-p}$ $T_A = 25^\circ\text{C}$	10			
		ICPLW2611 $I_F = 7.5\text{mA}$, $V_{OL} = 0.8\text{V}$ $V_E = V_{CC}$ $R_L = 350\Omega$ $V_{CM} = 400\text{Vp-p}$ $T_A = 25^\circ\text{C}$	20			

ISOLATION

Parameter	Symbol	Test Condition	Min	Typ.	Max	Unit
Isolation Voltage	V_{ISO}	$RH = 40-60\%$, $t = 1\text{min}$ $T_A = 25^\circ\text{C}$	5000			V_{RMS}

Device is considered a two terminal device : pins 1 to 4 are shorted together and pins 5 to 8 are shorted together.



ICPLW2601, ICPLW2611

ELECTRICAL CHARACTERISTICS

Notes :

- V_{CC} supply must be bypassed by a $0.1\mu F$ capacitor or larger with good frequency characteristics and should be connected as close as possible to the package V_{CC} and GND pins.
- Enable Input : No pull up resistor required as the device has an internal pull up resistor.
- t_{PLH} : measured from the 3.75mA level on the HIGH to LOW transition of the input current pulse to the 1.5V level on the LOW to HIGH transition of the output voltage pulse.
- t_{PHL} : measured from the 3.75mA level on the LOW to HIGH transition of the input current pulse to the 1.5 V level on the HIGH to LOW transition of the output voltage pulse.
- t_r : measured from the 10% to 90% level on the LOW to HIGH transition of the output voltage pulse.
- t_f : measured from the 90% to 10% level on the HIGH to LOW transition of the output voltage pulse.
- t_{ELH} : measured from the 1.5V level on the HIGH to LOW transition of the input Enable voltage pulse to the 1.5V level on the LOW to HIGH transition of the output voltage pulse.
- t_{EHL} : measured from the 1.5V level on the LOW to HIGH transition of the input Enable voltage pulse to the 1.5V level on the HIGH to LOW transition of the output voltage pulse.
- CM_H : the maximum tolerable rate of rise of the Common Mode voltage to ensure the output will remain in the HIGH state (i.e., $V_O > 2.0V$).
- CM_L : the maximum tolerable rate of rise of the Common Mode voltage to ensure the output will remain in the LOW state (i.e., $V_O < 0.8V$).

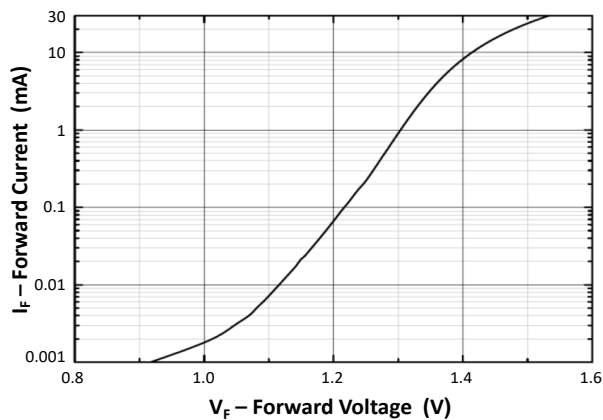


Fig 1 Forward Current vs Forward Voltage

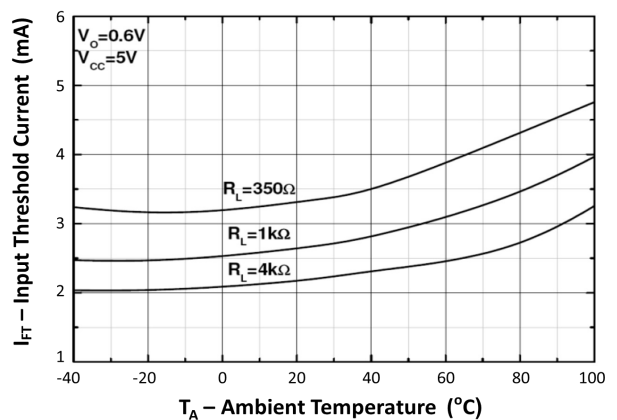


Fig 2 Input Threshold Current vs Ambient Temperature

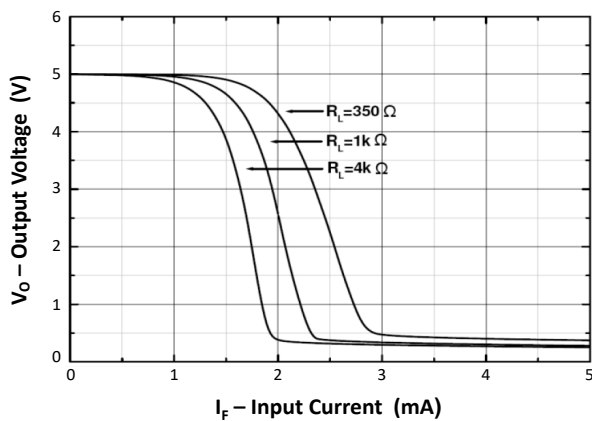


Fig 3 Output Voltage vs Input Current

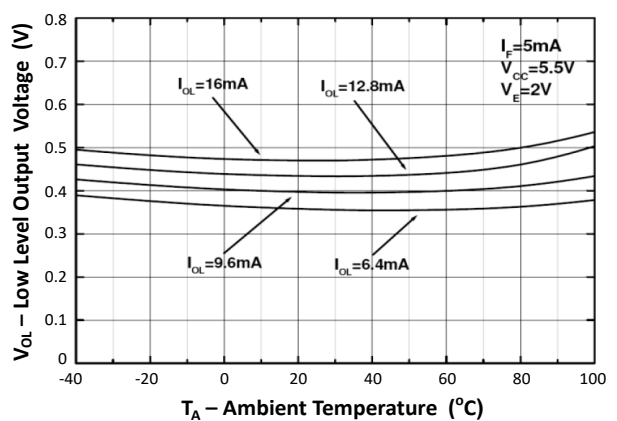


Fig 4 Low Level Output Voltage vs Ambient Temperature

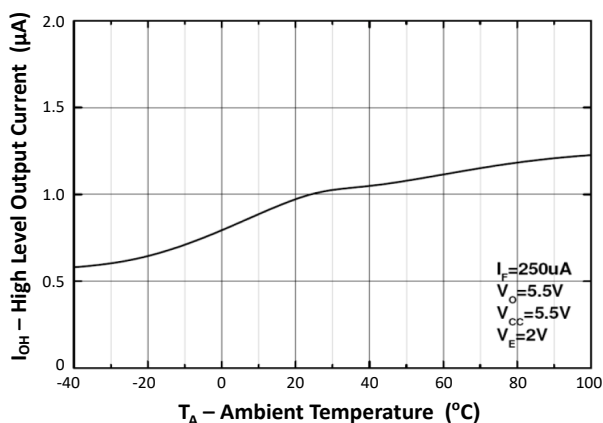


Fig 5 High Level Output Current vs Ambient Temperature

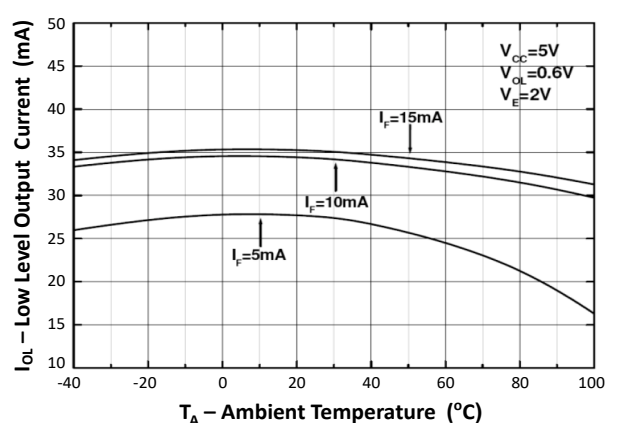


Fig 6 Low Level Output Current vs Ambient Temperature



ICPLW2601, ICPLW2611

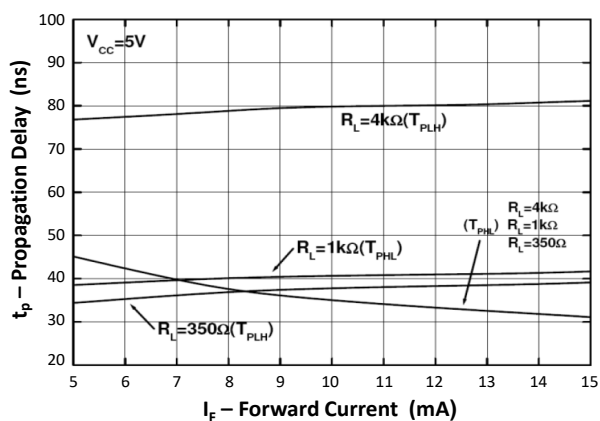


Fig 7 Propagation Delay vs Forward Current

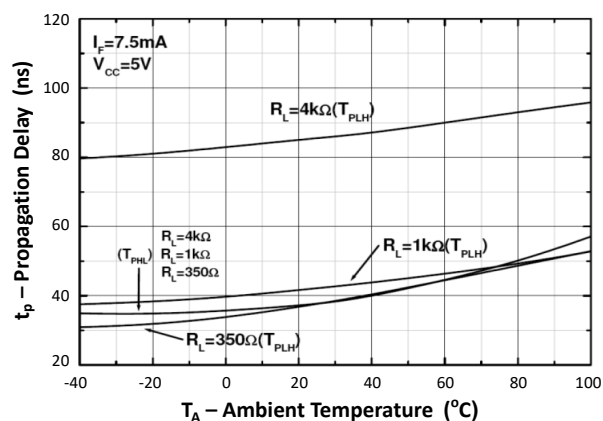


Fig 8 Propagation Delay vs Ambient Temperature

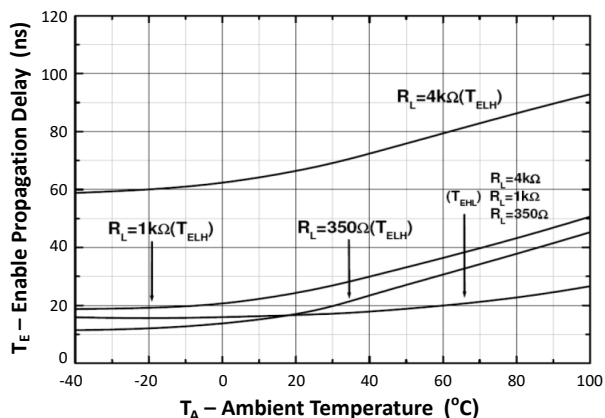


Fig 9 Enable Propagation Delay vs Ambient Temperature

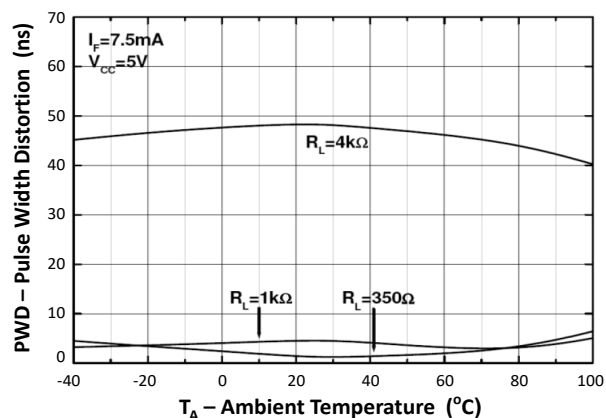


Fig 10 Pulse Width Distortion vs Ambient Temperature

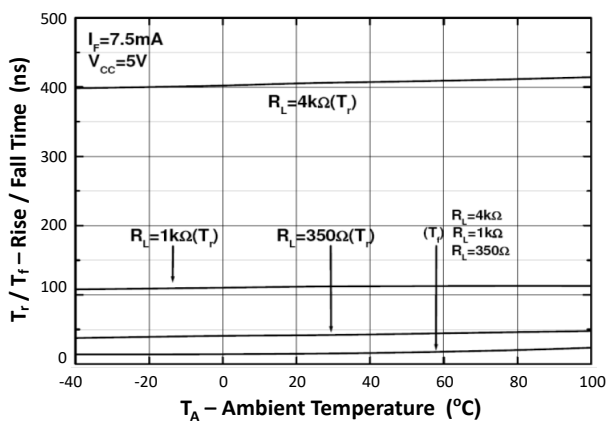
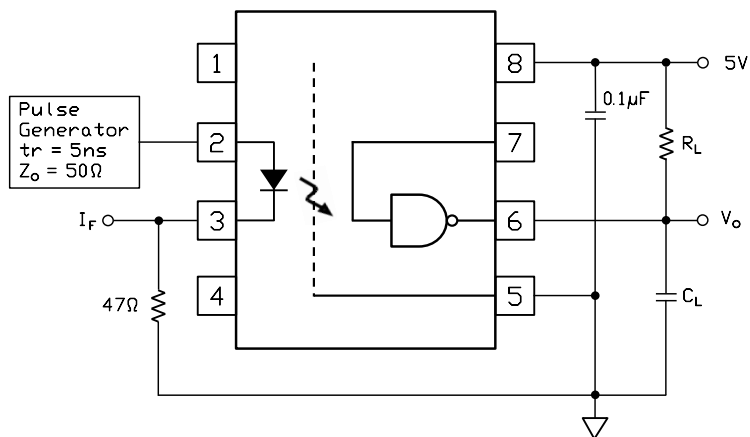


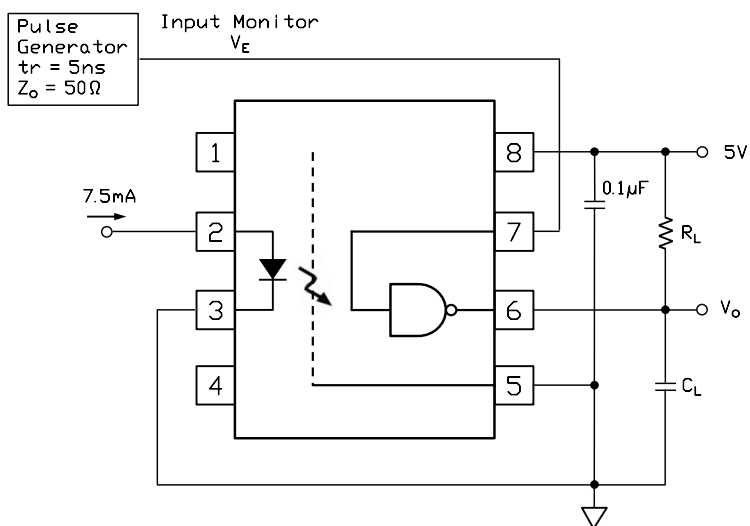
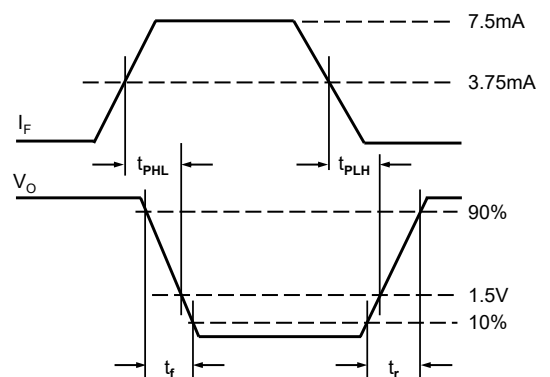
Fig 11 Rise Time / Fall Time vs Ambient Temperature



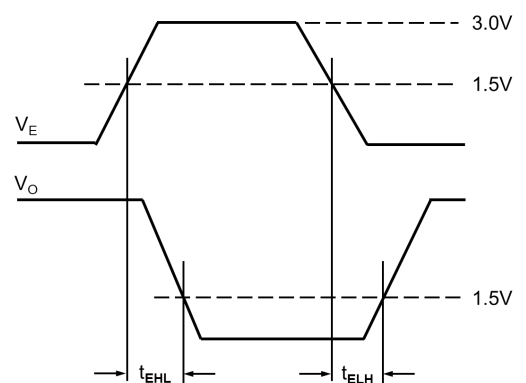
ICPLW2601, ICPLW2611



t_{PLH} , t_{PHL} , t_r and t_f Test Circuit

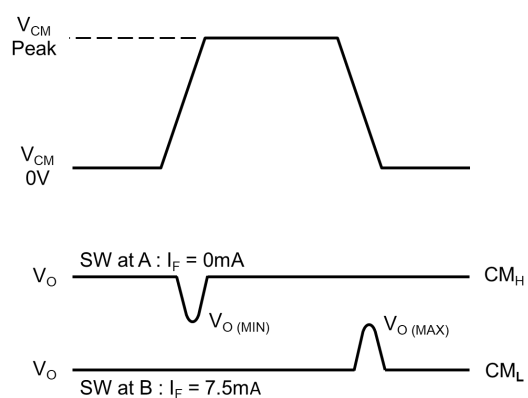
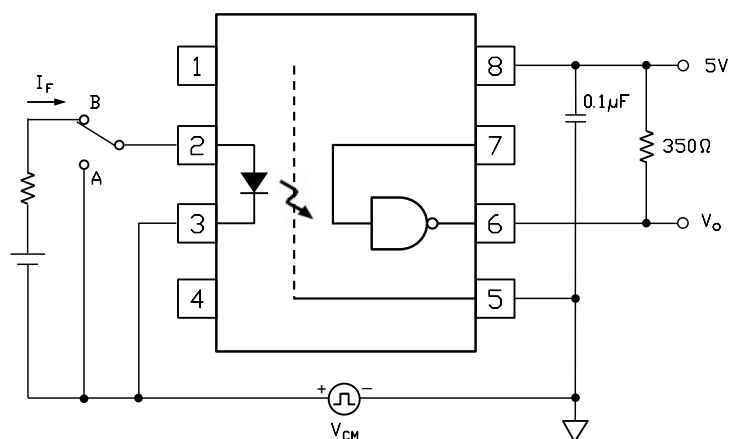


t_{ELH} and t_{EHL} Test Circuit

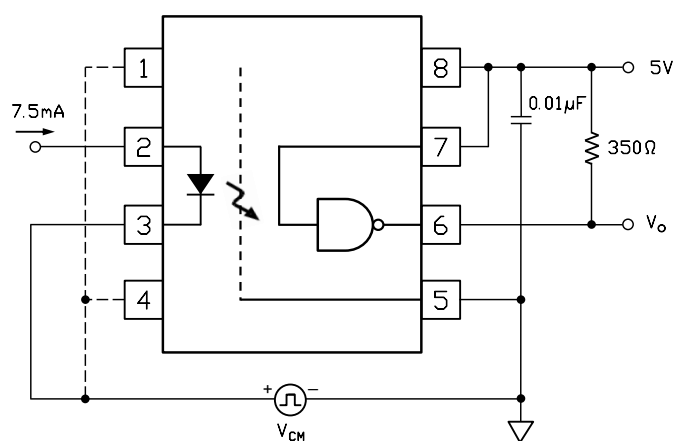




ICPLW2601, ICPLW2611



Common Mode Transient Immunity Test Circuit



ICPLW2611 : Recommended Drive Circuit for High Common Mode Transient Immunity

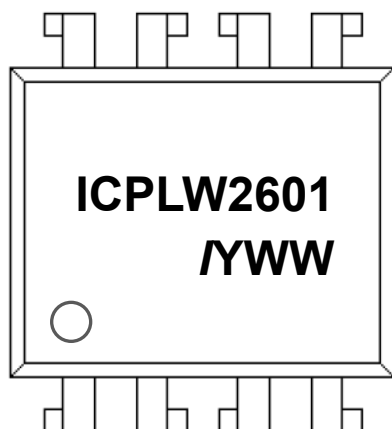
ICPLW2601, ICPLW2611

ORDER INFORMATION

ICPLW2601, ICPLW2611			
After PN	PN	Description	Packing quantity
None	ICPLW2601, ICPLW2611	Wide Body DIP8	40 pcs per tube
SM	ICPLW2601SM, ICPLW2611SM	Surface Mount	40 pcs per tube
SMT&R	ICPLW2601SMT&R ICPLW2611SMT&R	Surface Mount Tape & Reel	500 pcs per reel

DEVICE MARKING

Example : ICPLW2601



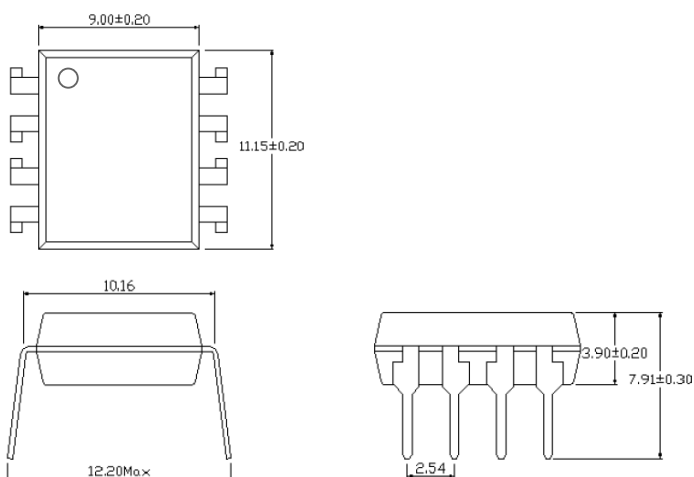
ICPLW2601	denotes Device Part Number
/	denotes Isocom
Y	denotes Year code
WW	denotes 2 digit Week Code



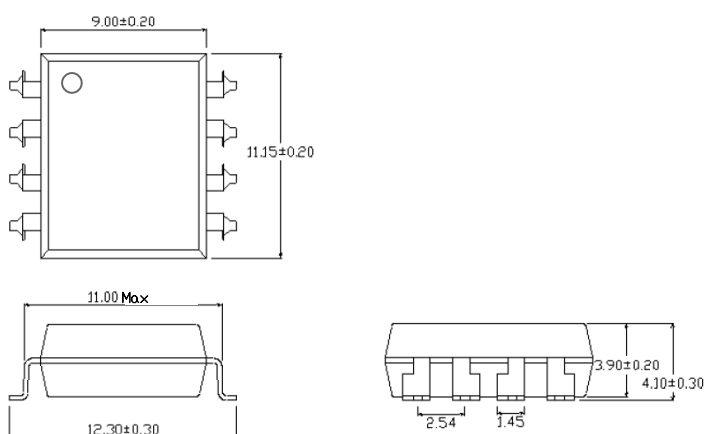
ICPLW2601, ICPLW2611

PACKAGE DIMENSIONS (mm)

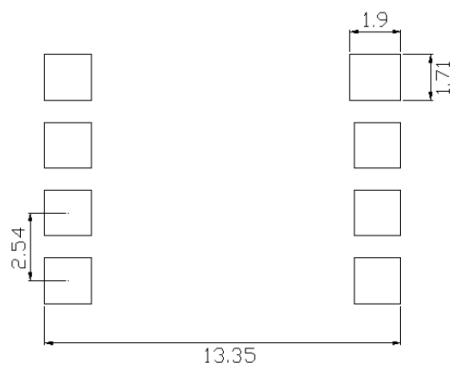
DIP



SMD



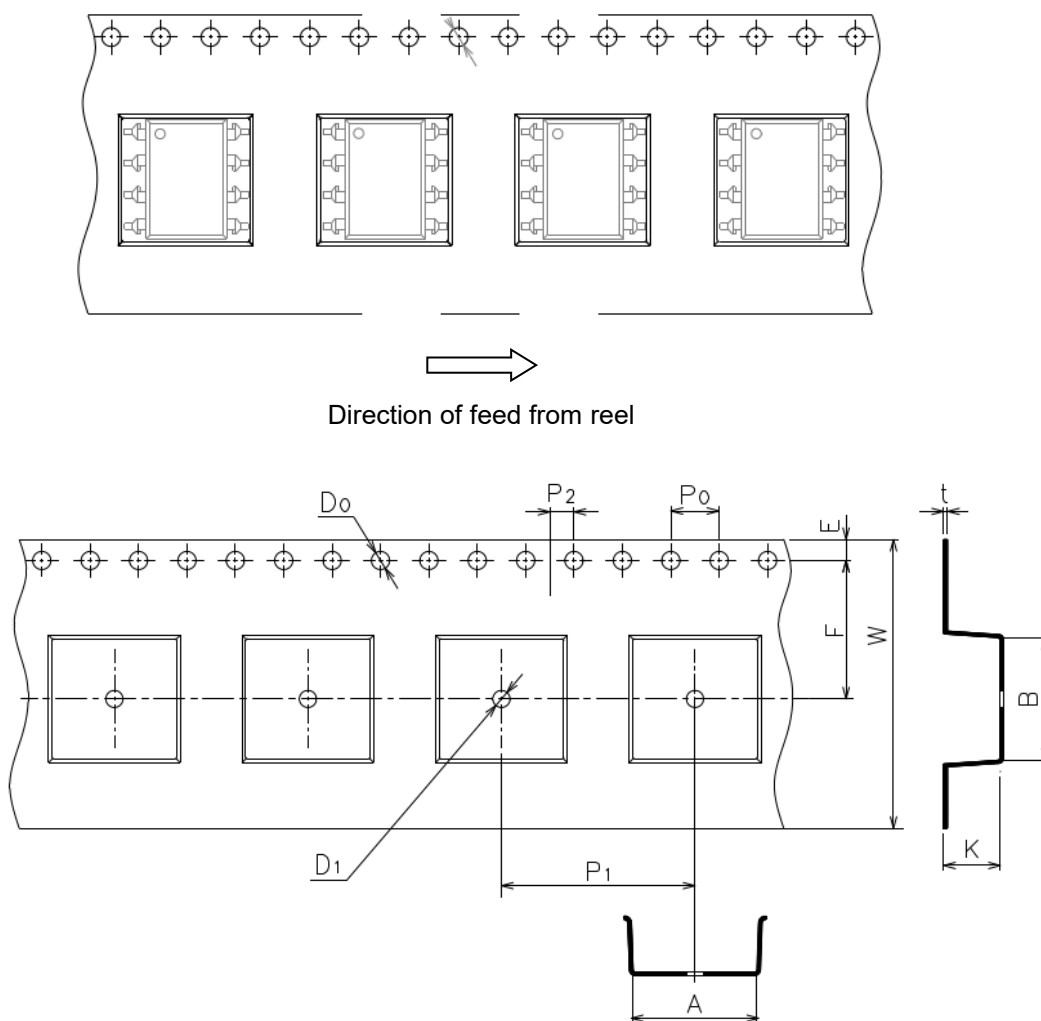
RECOMMENDED PAD LAYOUT FOR SMD (mm)





ICPLW2601, ICPLW2611

TAPE AND REEL PACKAGING



Dimension	A	B	D ₀	D ₁	E	F
mm	12.7±0.1	11.45±0.1	1.5±0.1	1.5±0.1	1.75±0.1	11.5±0.1
Dimension	P ₀	P ₁	P ₂	t	W	K
mm	4.0±0.1	16.0±0.1	2.0±0.1	0.4±0.05	24.00±0.3	4.6±0.1

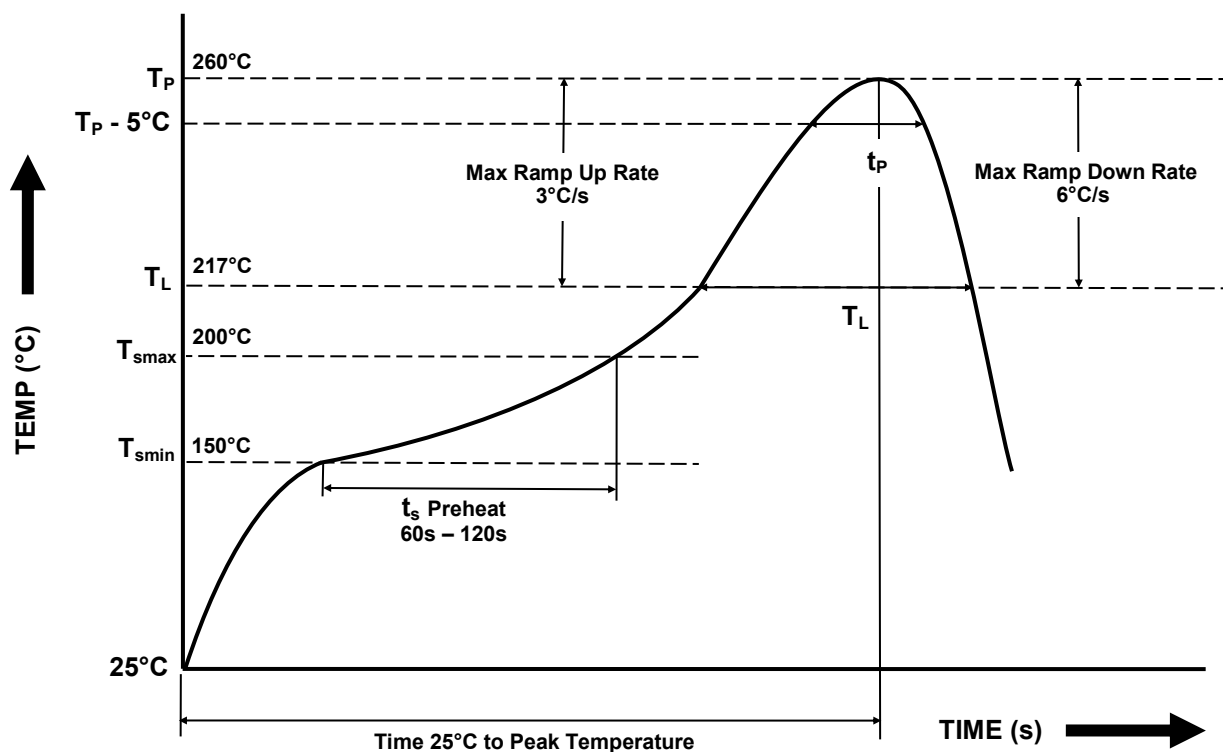


ICPLW2601, ICPLW2611

IR REFLOW SOLDERING TEMPERATURE PROFILE

One Time Reflow Soldering is Recommended.

Do not immerse device body in solder paste.



Profile Details	Conditions
Preheat <ul style="list-style-type: none">- Min Temperature (T_{SMIN})- Max Temperature (T_{SMAx})- Time T_{SMIN} to T_{SMAx} (t_s)	150°C 200°C 60s - 120s
Soldering Zone <ul style="list-style-type: none">- Peak Temperature (T_P)- Time at Peak Temperature- Liquidous Temperature (T_L)- Time within 5°C of Actual Peak Temperature (T_P – 5°C)- Time maintained above T_L (t_L)- Ramp Up Rate (T_L to T_P)- Ramp Down Rate (T_P to T_L)	260°C 10s max 217°C 30s max 60s - 100s 3°C/s max 6°C/s max
Average Ramp Up Rate (T _{smax} to T _P)	3°C/s max
Time 25°C to Peak Temperature	8 minutes max

DISCLAIMER

Isocom Components is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing Isocom Components products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such Isocom Components products could cause loss of human life, bodily injury or damage to property.

In developing your designs, please ensure that Isocom Components products are used within specified operating ranges as set forth in the most recent Isocom Components products specifications.

The Isocom Components products listed in this document are intended for usage in general electronics applications (computer, personal equipment, office equipment, measuring equipment, industrial robotics, domestic appliances, etc.). These Isocom Components products are neither intended nor warranted for usage in equipment that requires extraordinarily high quality and/or reliability or a malfunction or failure of which may cause loss of human life or bodily injury ("Unintended Usage"). Unintended Usage include atomic energy control instruments, airplane or spaceship instruments, transportation Instruments, traffic signal instruments, combustion control instruments, medical Instruments, all types of safety devices, etc... Unintended Usage of Isocom Components products listed in this document shall be made at the customer's own risk.

Gallium arsenide (GaAs) is a substance used in the products described in this document. GaAs dust and fumes are toxic. Do not break, cut or pulverize the product, or use chemicals to dissolve them. When disposing of the products, follow the appropriate regulations. Do not dispose of the products with other industrial waste or with domestic garbage.

The products described in this document are subject to the foreign exchange and foreign trade laws.

The information contained herein is presented only as a guide for the applications of our products. No responsibility is assumed by Isocom Components for any infringements of intellectual property or other rights of the third parties which may result from its use. No license is granted by implication or otherwise under any intellectual property or other rights of Isocom Components or others.

The information contained herein is subject to change without notice.